

L Number	Hits	Search Text	DB	Time stamp
1	5	(plurality adj (insulating or insulation or insulative or dielectric) adj (layers or films)) with voids	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:26
2	19	(plurality adj (insulating or insulation or insulative or dielectric) adj (layers or films)) same voids	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:38
3	661	(plurality adj (insulating or insulation or insulative or dielectric) adj (layers or films)) same (holes or vias or openings)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 13:35
4	105	(plurality adj (insulating or insulation or insulative or dielectric) adj (layers or films)) same (gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:20
5	42	multilayer adj passivation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:22
6	15	multiple adj passivation adj (layers or films)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:23
7	27	plurality adj passivation adj (layers or films)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:24
8	1	multi adj passivation adj (layers or films)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:24
9	0	multipassivation adj (layers or films)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:36
10	0	multiplicity adj passivation adj (layers or films)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:25
11	5	stacked adj passivation adj (layers or films)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:25
12	681	(stacked adj (insulating or insulation or insulative or dielectric) adj (layers or films))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:26
13	7	multilayered adj passivation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:37
14	6	multi adj layered adj passivation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:37

15	0	multiple adj layered adj passivation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 10:37
16	167	multi adj (insulating or insulation or insulative or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 11:23
17	0	5252520.pn. and (apect adj ratio)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 11:24
18	0	5252520.pn. and (aspect adj ratio)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 11:24
20	1290	((aspect adj ratio) with opening) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 11:25
21	7	(plurality adj (insulating or insulation or insulative or dielectric) adj (layers or films)) same (holes or vias or openings) same (aspect adj ratio)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 13:42
22	2	6384466.pn. and (aspect adj ratio)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 16:32
23	2748	438/624.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 13:47
24	271	438/624.ccls. and (aspect adj ratio)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 13:48
25	43	438/624.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 13:58
26	11	438/641.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:00
27	45	438/643.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 15:20
28	26	438/668.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:05
29	4	438/257.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:06

30	17	438/435.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:08
31	10	438/427.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:10
32	31	438/424.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 14:10
33	921	438/\$.ccls. and ((aspect adj ratio) with "2")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 15:20
34	1	5807785.pn. and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 16:03
35	2	5861345.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/18 16:33